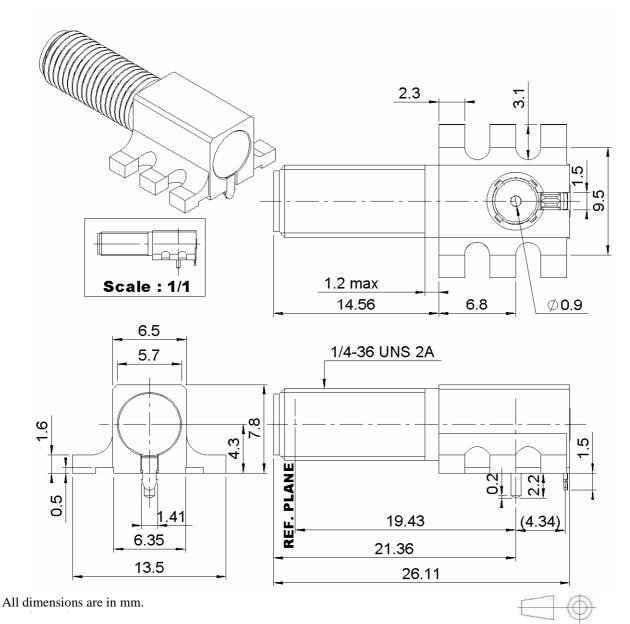
### **REEL PACKAGING PER 250**

R124.682.833

Series: SMA-COM



| COMPONENTS   | MATERIALS                   | PLATING (μm)     |
|--|-----------------------------|------------------|
| BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET | BRASS BERYLLIUM COPPER PTFE | NPGR<br>NPGR     |
| OTHERS PARTS -                                     | BRASS<br>-<br>-             | GOLD OVER COPPER |

**Issue:** 1222 C

In the effort to improve our products, we reserve the right to make changes judged to be



#### **REEL PACKAGING PER 250**

R124.682.833

Series: SMA-COM

#### **PACKAGING**

| Standard | Unit       | Other      |
|----------|------------|------------|
| 250      | 'W' option | Contact us |

### **SPECIFICATION**

# **ELECTRICAL CHARACTERISTICS**

Impedance **50** Ω Frequency **0-18** GHz

**VSWR** \*1.15 + 0,0400 x F(GHz) Maxi

Insertion loss **0.16**  $\sqrt{F(GHz)}$  dB Maxi RF leakage **90** - F(GHz)) dB Maxi - (

Voltage rating 350 Veff Maxi Dielectric withstanding voltage 1000 Veff mini Insulation resistance **5000** M $\Omega$  mini

### **ENVIRONMENTAL**

**-65/+165** ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

## **OTHER CHARACTERISTICS**

Assembly instruction NA

Others:

\*Coaxial transmission line only

## **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end 15 N mini Axial force – Opposite end 15 N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut 110 N.cm

Mating life 100 Cycles mini

**7,6630** g Weight

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#### **SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

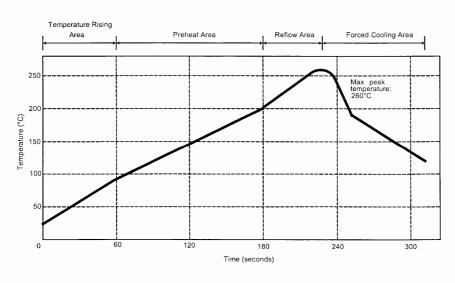
We advise a thickness of 150 micronmm (5.850 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

#### TEMPERATURE PROFILE



**Issue**: 1222 C

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necessary.



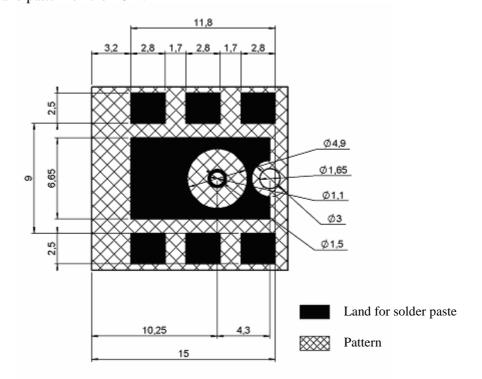
# REEL PACKAGING PER 250

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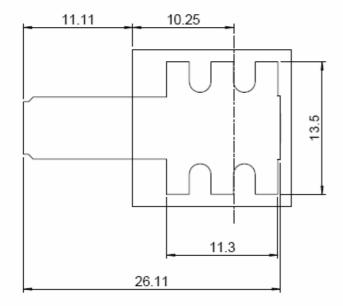
Series: **SMA-COM** 

#### **SMA SERIES - INFORMATION**

Coplanar line : pattern and signal are on the same side . Thickness of PCB : .063(1.6mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed exept for the land pattern on the PCB .



#### SHADOW OF SMA RECEPTACLE FOR VIDEO CAMERA



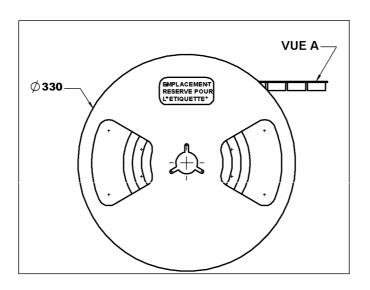
**Issue:** 1222 C
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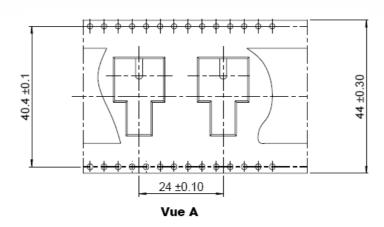
### **REEL PACKAGING PER 250**

R124.682.833

Series: SMA-COM



bobine Ech: 0.7



Note: Reel package don't include nut and washer, which are packaged in box.

 $\begin{tabular}{l} \textbf{Issue:} 1222 & C \\ \textbf{In the effort to improve our products, we reserve the right to make changes judged to be} \\ \end{tabular}$ 

